



Docket No.: 55551 CIP (71360)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Kanayama, et al.

EXAMINER: D. J. Buttner

SERIAL NO.: 09/768,931

GROUP: 1712

FILED: January 24, 2001

FOR: THERMOPLASTIC RESIN COMPOSITION MOLDED PRODUCT
AND USE

Honorable Commissioner of Patents and Trademarks
Washington, DC 20231

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CERTIFICATE OF MAILING

I, Maggie C. Hamelin, hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage by First Class Mail, in an envelope addressed to: The Assistant Commissioner for Patents, Washington, DC 20231.

Date: August 1, 2002

Maggie C Hamelin
Maggie C. Hamelin

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated March 5, 2002 and request reconsideration of the above-identified application in view of the following amendments and remarks.

IN THE SPECIFICATION:

Kindly amend the Title of the Invention, on page 1, as follows:

THERMOPLASTIC RESIN COMPOSITION, MOLDED PRODUCT AND USE

Kindly amend the Cross Reference to Related Application, on page 1, as follows:

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